

# **Customer Information Notification**

05-Mar-2020 Issue Date: **Effective Date:** 06-Mar-2020

Dear PCN NXP.

Please find below a Quality Notification that has been distributed by NXP.

## 2019110271



Change	Category
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Change Calegory				
[] Wafer Fab Process	'	[] Product Marking	[] Test	[] Design
	Process		Location	
[] Wafer Fab Materials	[] Assembly	[] Mechanical Specification	n[]Test	[] Errata
	Materials		Process	
[] Wafer Fab Location	[] Assembly	[]	[] Test	[X] Electrical
Loc	Location	Packing/Shipping/Labeling	Equipment	spec./Test
				coverage

[] Firmware [] Other

MPC5604E and MPC5606E Datasheet **Update** 

### **Description**

NXP Semiconductors announces Datasheet update for MPC5604E and MPC5606E. The revision history included in the updated documents provides a detailed description of the changes.

A file containing the summary of all changes to these documents is attached with this notification.

- 1. MPC5604E update from revision 5.1 to revision 6 The MPC5604E Datasheet revision 6 is attached to this notice and can be found at https://www.nxp.com/products/processors-and-microcontrollers/power-architecture/mpc55xx-5xxxmcus/ultra-reliable-mpc56xx-mcus/ultra-reliable-32-bit-mcu-for-automotive-adas-and-industrial-ethernetapplications:MPC560xE?tab=Documentation Tab
- 2. MPC5606E update from revision 2 to revision 3 The MPC5606E Datasheet revision 3 is attached to this notice and can be found at https://www.nxp.com/products/processors-and-microcontrollers/power-architecture/mpc55xx-5xxxmcus/ultra-reliable-mpc56xx-mcus/ultra-reliable-32-bit-mcu-for-automotive-adas-and-industrial-ethernetapplications:MPC560xE?tab=Documentation Tab

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-03

#### Reason

The Datasheet has been updated to correct errors and provide additional technical clarification on some device features.

#### **Identification of Affected Products**

Product identification does not change

### Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

#### **Data Sheet Revision**

A new datasheet will be issued

#### **Additional information**

Affected products and sales history information: see attached file

Additional documents: view online

#### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

NameMinghao XuPositionProduct Engineere-mail addressMinghao.xu@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they

reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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